

1

2

3

4

5

6

A

B

C

D

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
E	30	31.00mil (0.787mm)	NPTH	Round	Top Copper - Bottom Copper	+/-3.00mil
⬇	2	35.43mil (0.900mm)	NPTH	Round	Top Copper - Bottom Copper	
▽	2	50.00mil (1.270mm)	NPTH	Round	Top Copper - Bottom Copper	
⊗	2	106.00mil (2.692mm)	NPTH	Round	Top Copper - Bottom Copper	
✖	131	7.87mil (0.200mm)	PTH	Round	Top Copper - Bottom Copper	
▽	1734	8.00mil (0.203mm)	PTH	Round	Top Copper - Bottom Copper	
A	2	8.00mil (0.203mm)	PTH	Round	Top Copper - Bottom Copper	+/-3.00mil
⊗	137	10.00mil (0.254mm)	PTH	Round	Top Copper - Bottom Copper	
⊗	96	10.00mil (0.254mm)	PTH	Round	Top Copper - Bottom Copper	+/-3.00mil
B	12	15.00mil (0.381mm)	PTH	Round	Top Copper - Bottom Copper	
F	16	15.75mil (0.400mm)	PTH	Round	Top Copper - Bottom Copper	
⊗	56	40.00mil (1.016mm)	PTH	Round	Top Copper - Bottom Copper	
⊗	14	40.16mil (1.020mm)	PTH	Round	Top Copper - Bottom Copper	
✖	3	45.28mil (1.150mm)	PTH	Round	Top Copper - Bottom Copper	
✖	56	59.06mil (1.500mm)	PTH	Round	Top Copper - Bottom Copper	
✖	4	77.95mil (1.980mm)	PTH	Round	Top Copper - Bottom Copper	
⊗	4	125.98mil (3.200mm)	PTH	Round	Top Copper - Bottom Copper	
C	2	100.00mil (2.540mm)	NPTH	Slot	Top Copper - Bottom Copper	+/-5.00mil
D	2	100.00mil (2.540mm)	NPTH	Slot	Top Copper - Bottom Copper	+/-5.00mil
◇	2	29.92mil (0.760mm)	PTH	Slot	Top Copper - Bottom Copper	
■	1	39.76mil (1.010mm)	PTH	Slot	Top Copper - Bottom Copper	
2308 Total						

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top SilkScreen				
	Top Solder Mask	TAIYO-4000-BN	0.50mil	3.9	
1	Top Copper	Copper	2.00mil		COPPER + PLATING
	Dielectric 1	MEG6-R-5775K	6.00mil	3.42	
2	Layer 2 (GND1)	Copper	0.60mil		
	Dielectric 2	MEG6-R-5670K	3.30mil	3.23	
3	Layer 3 (SIG1)	Copper	0.60mil		
	Dielectric 3	MEG6-R-5775K	3.00mil	3.42	
4	Layer 4 (GND2)	Copper	0.60mil		
	Dielectric 4	MEG6-R-5670K	3.50mil	3.23	
5	Layer 5 (PWR1)	Copper	1.20mil		
	Dielectric 5	MEG6-R-5775K	2.60mil	3.58	
6	Layer 6 (GND3)	Copper	1.20mil		
	Dielectric 6	MEG6-R-5670K	3.00mil	3.23	
7	Layer 7 (PWR/SIGNAL2)	Copper	1.20mil		
	Dielectric 7	MEG6-R-5775K	3.00mil	3.42	
8	Layer 8 (PWR/SIGNAL3)	Copper	1.20mil		
	Dielectric 8	MEG6-R-5670K	3.00mil	3.23	
9	Layer 9 (GND4)	Copper	1.20mil		
	Dielectric 9	MEG6-R-5775K	2.60mil	3.58	
10	Layer 10 PWR2)	Copper	1.20mil		
	Dielectric 10	MEG6-R-5670K	3.50mil	3.23	
11	Layer 11 (GND5)	Copper	0.60mil		
	Dielectric 11	MEG6-R-5775K	3.00mil	3.42	
12	Layer 12 (SIG4)	Copper	0.60mil		
	Dielectric 12	MEG6-R-5670K	3.30mil	3.23	
13	Layer 13 (GND6)	Copper	0.60mil		
	Dielectric 13	MEG6-R-5775K	6.00mil	3.42	
14	Bottom Copper	Copper	2.00mil		COPPER + PLATING
	Bottom Solder Mask	TAIYO-4000-BN	0.50mil	3.9	
	Bottom Silk				

Board Edge

2750.0mil

10400.0mil

ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: N/A

REV: E2

SUN REV: Not In VersionControl

TEXAS INSTRUMENTS (TI) and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. TI and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. TI and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.

LAYER NAME = M2 Board Dimensions

PLOT NAME = Fabrication Drawing

GENERATED : 20-Sep-21 6:25:35 AM

TEXAS INSTRUMENTS

DESIGN INFORMATION

MIN. TRACK WIDTH: 4 MIL
MIN. CLEARANCE: 5 MIL
MIN. VIA PAD SIZE: 16 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
☐ FR-408 ☐ ISOLA FR4-370HR
☐ Meg4 ☐ Isola I-Speed
☒ Meg6 ☐ Isola MT-40 ☐ Nelco MW-1000
☒ OTHER Meg6 Equivalent

THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER

TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/-

BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/-

DRILLING:
REFERENCE: ☒ AS SHOWN ☒ NC_DRILL FILES
PTH COPPER THICKNESS: ☒ 20-30 um ☐ OTHER

BOARD FINISH:
SILKSCREEN: ☒ TOP ☒ BOTTOM
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER
SOLDER RESIST COLOR: ☐ GREEN ☒ OTHER RED
☒ MATTE ☐ SEMI-GLOSS

SURFACE FINISH: ☒ IMMERSION GOLD (ENIG) ☐ ENEPIG
☐ IMM. TIN/SILVER OR EQUIV ☐ HARD GOLD (30u)
☐ OTHER

ARRAY/PANEL: ☐ CUT AND TRIM PER M1 BOARD OUTLINE
☐ N.C. ROUTE ☒ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3
☒ RoHS ☐ OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: ☐ YES
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER
☒ 16 MIL & SMALLER VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
☒ OUTER LAYER TRACKS 11.5 MIL WIDE REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
☒ OUTER LAYER TRACKS 10.5 MIL WIDE WITH 20.5 MIL SPACE REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE
☐ INNER LAYER XX & XX TRACKS XX MIL WIDE REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
☐ INNER LAYER 03 & 12 TRACKS 3.25 MIL WIDE WITH 8 MIL SPACE REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

☒ NO VENDOR LOGO OR NAME ON THE BOARD
☒ HOLES LESS THAN 12 MIL ARE DRILL SIZES AND NOT FINISHED HOLE SIZES (FHS)

TEXAS INSTRUMENTS

PROJECT TITLE:
ADC12DJ5200RF EVM

DESIGNED FOR:
TI

FILE NAME:
ADC12DJ5200RF EVM

ENGINEER:
DWG

LAYOUT BY:
BMR

print_Scale: 1:1

ALTUM DESIGNER VERSION:
305-PD18-0843

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